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# HVM14SR

Silicon Epitaxial Planar PIN Diode for High Frequency Attenuator

# HITACHI

ADE-208-084C(Z)

Rev. 3  
Feb. 1999

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## Features

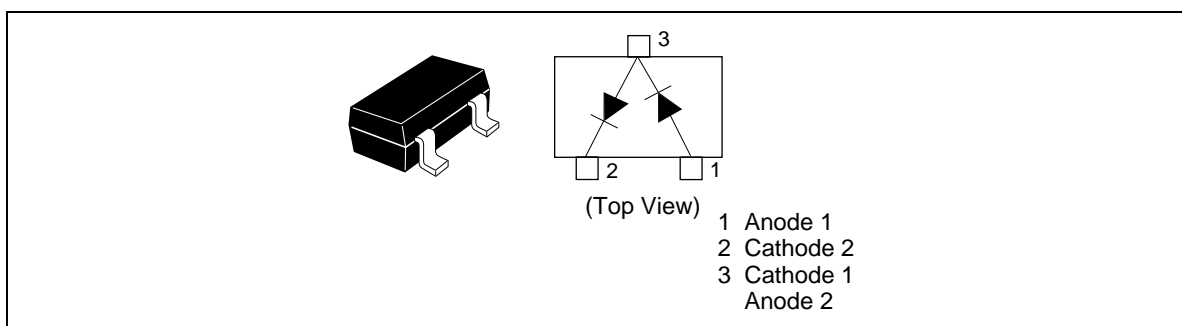
- Low forward resistance. ( $r_f = 7.0\Omega_{\max}$ )
- Low capacitance. ( $C = 0.25\text{pF typ}$ )
- MPAK package is suitable for high density surface mounting and high speed assembly.

## Ordering Information

Type No.	Laser Mark	Package Code
HVM14SR	H7	MPAK

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## Outline



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## HVM14SR

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### Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Value	Unit
Reverse voltage	$V_R$	50	V
Forward current	$I_F$	50	mA
Power dissipation	$P_d^{*1}$	100	mW
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-55to+125	°C

Note: 1. Two device total.

### Electrical Characteristics <sup>\*2</sup>

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Condition
Forward voltage	$V_F$	—	—	1.0	V	$I_F = 50 \text{ mA}$
Reverse current	$I_R$	—	—	100	nA	$V_R = 50\text{V}$
Capacitance	C	—	0.25	—	pF	$V_R = 50\text{V}, f = 1 \text{ MHz}$
Forward resistance	$r_f$	—	—	7	$\Omega$	$I_F = 10 \text{ mA}, f = 100 \text{ MHz}$
ESD-Capability <sup>*1</sup>	—	200	—	—	V	C=200pF, Both forward and reverse direction 1 pulse

Note: 1. Failure criterion ;  $I_R \geq 200\text{nA}$  at  $V_R = 50 \text{ V}$

Note: 2. Per one device.

Main Characteristic

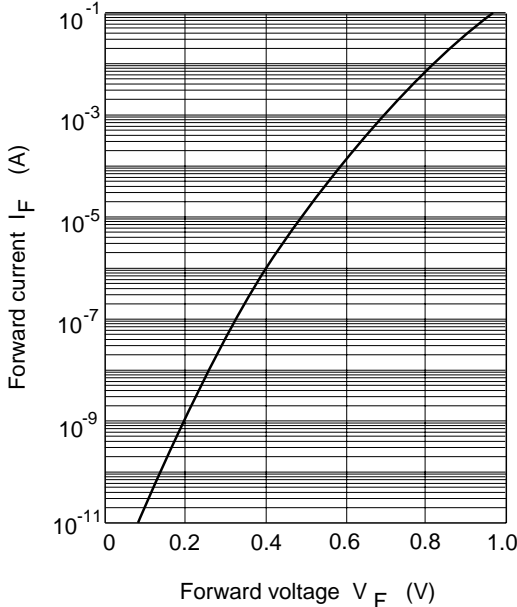


Fig.1 Forward current Vs. Forward voltage

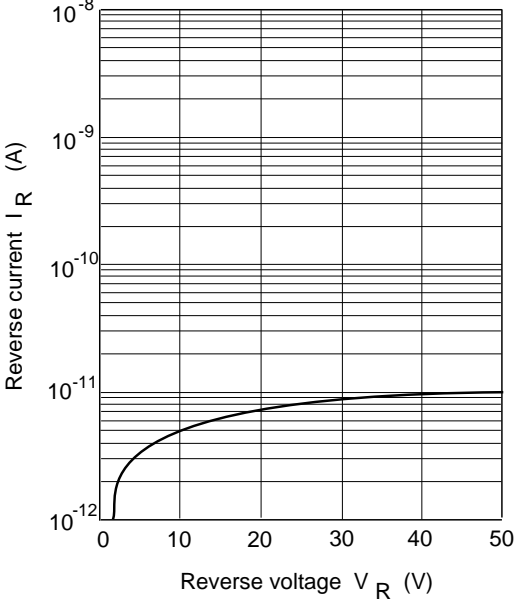


Fig.2 Reverse current Vs. Reverse voltage

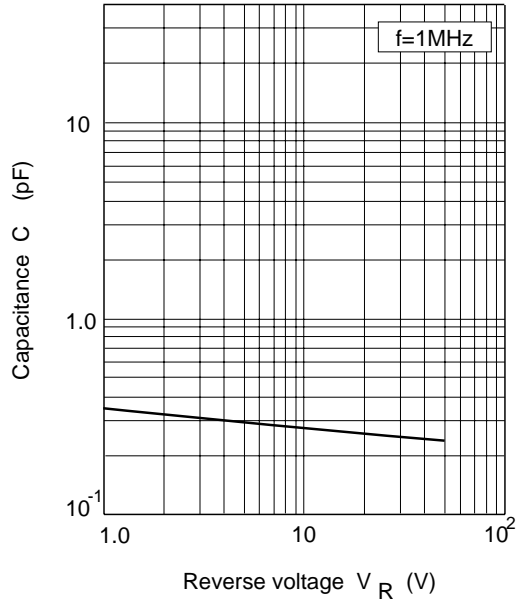


Fig.3 Capacitance Vs. Reverse voltage

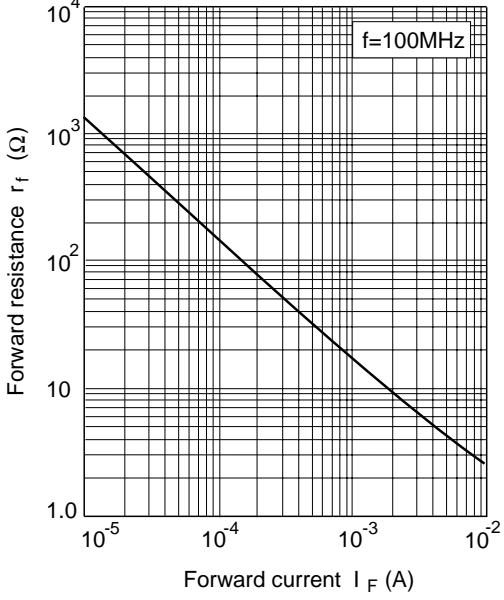
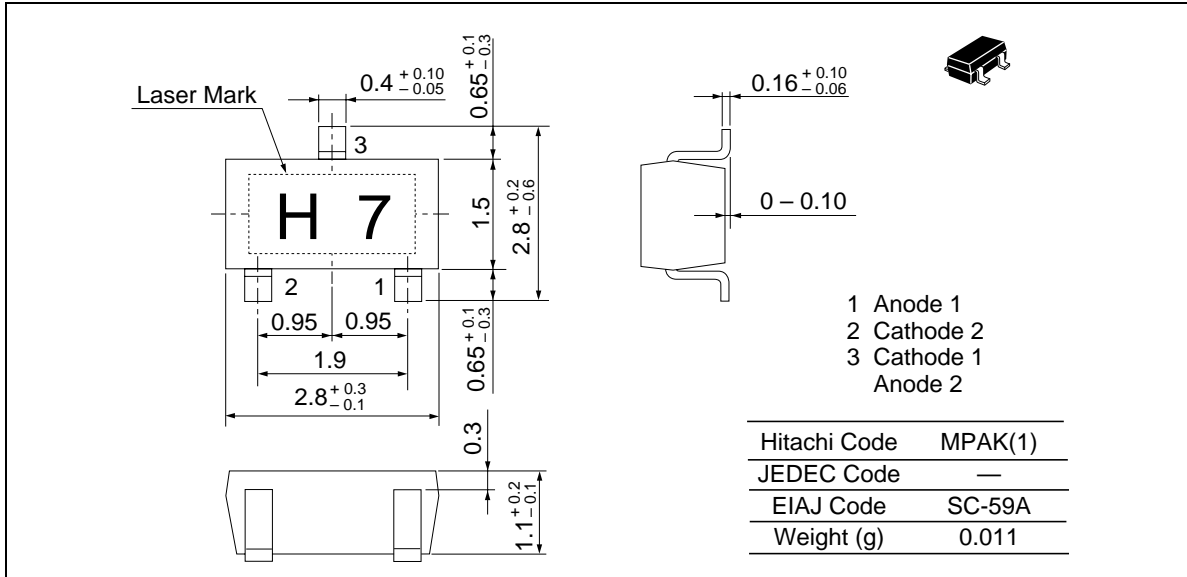


Fig.4 Forward resistance Vs. Forward current

# HVM14SR

## Package Dimensions

Unit : mm



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# HITACHI

### Hitachi, Ltd.

Semiconductor & Integrated Circuits  
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan  
Tel: (03) 3270-2111 Fax: (03) 3270-5109

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### For further information write to:

Hitachi Semiconductor  
(America) Inc.  
179 East Tasman Drive  
San Jose, CA 95134  
Tel: <1> (408) 433-1990  
Fax: <1> (408) 433-0223

Hitachi Europe Ltd.  
Electronic Components Group  
Whitebrook Park  
Lower Cookham Road  
Maidenhead  
Berkshire SL6 8YA, United Kingdom  
Tel: <44> (1628) 585000  
Fax: <44> (1628) 585200

Hitachi Europe GmbH  
Electronic Components Group  
Dornacher Straße 3  
D-85622 Feldkirchen, Munich  
Germany  
Tel: <49> (89) 9 9180-0  
Fax: <49> (89) 9 29 30 00

Hitachi Asia Ltd.  
Hitachi Tower  
16 Collyer Quay #20-00  
Singapore 049318  
Tel: <65>-538-6533/538-8577  
Fax: <65>-538-6933/538-3877  
URL: <http://www.hitachi.com.sg>

Hitachi Asia Ltd.  
(Taipei Branch Office)  
4/F, No. 167, Tun Hwa North Road  
Hung-Kuo Building  
Taipei (105), Taiwan  
Tel: <886>-(2)-2718-3666  
Fax: <886>-(2)-2718-8180  
Telex: 23222 HAS-TP  
URL: <http://www.hitachi.com.tw>

Hitachi Asia (Hong Kong) Ltd.  
Group III (Electronic Components)  
7/F., North Tower  
World Finance Centre,  
Harbour City, Canton Road  
Tsim Sha Tsui, Kowloon  
Hong Kong  
Tel: <852>-(2)-735-9218  
Fax: <852>-(2)-730-0281  
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